

LISTING OF CLAIMS:

1. (Currently amended) A pressure sensitive adhesive sheet, comprising a base material and a pressure sensitive adhesive layer in which a plurality of through holes passing through one face to the other face are formed, wherein

the hole diameter of the through holes at the base material and the pressure sensitive adhesive layer is 0.1 to ~~300 μ m~~300 μ m,

the hole diameter of the through holes at a front surface of the pressure sensitive adhesive sheet is 40 μ m or less, and

the hole density is 30 to 50,000/100 cm².

2. (Canceled)

3. (Currently amended) The pressure sensitive adhesive sheet according to ~~claim 1~~ or claim 1, wherein the through holes are formed by a laser beam machining.

4. (Withdrawn) A method for production of pressure sensitive adhesive sheet, comprising the steps of; preparing a pressure sensitive adhesive sheet comprising a base material, a pressure sensitive adhesive layer and, as desired, further a release material, and performing a hole-forming processing on the pressure sensitive adhesive sheet to form through holes such that the hole diameter at the base material and the pressure sensitive adhesive layer is 0.1 to 300 μ m and the hole density is 30 to 50,000/100 cm².

5. (Withdrawn) The method for production of pressure sensitive adhesive sheet according to claim 4, wherein the hole-forming processing is a laser beam machining.

6. (Withdrawn) The method for production of pressure sensitive adhesive sheet according to claim 5, wherein the laser beam machining is performed from the back surface side of the pressure sensitive adhesive sheet.

7. (Withdrawn) The method for production of pressure sensitive adhesive sheet according to claim 6, wherein a laser is directly radiated to the pressure sensitive adhesive layer.

8. (Withdrawn) The method for production of pressure sensitive adhesive sheet according to claim 6, wherein the release material laminated on the pressure sensitive adhesive layer is peeled from the pressure sensitive adhesive layer, a laser is directly radiated to the pressure sensitive adhesive layer, and then the release material is laminated again on the pressure sensitive adhesive layer.

9. (Withdrawn) The method for production of pressure sensitive adhesive sheet according to any one of claims 4 to 8, wherein the laser beam machining is performed while a process material or a removable protective sheet is laminated on the surface of the base material.

10. (New) The pressure sensitive adhesive sheet according to claim 1, wherein the base material is transparent, and the hole diameter of the through hole in the base material and the pressure sensitive adhesive layer is 0.1 to 60 μm .

11. (New) A pressure sensitive adhesive sheet, comprising a base material and a pressure sensitive adhesive layer in which a plurality of through holes passing through one face to the other face are formed, wherein the hole diameter of the through holes at the base material and the pressure sensitive adhesive layer is 0.1 to 300 μm , and the through holes are formed by laser beam machining.

12. (New) The pressure sensitive adhesive sheet according to claim 1 or claim 11, wherein the hole diameter of the through holes gradually decreases from a back surface to a front surface of the pressure sensitive adhesive sheet.